FORM PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

APPLICATION NO. 09/973,854

## INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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| APPLICAN Chopra et          |        |               | COPY OF PAPERS   |
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|                     |                 |      | U.S. PATENT DOCUMENTS    |       |          |                                 |    |  |
| EXAMINER<br>INITIAL | DOCUMENT NUMBER | DATE | NAME                     | CLASS | SUBCLASS | FILING DATE<br>(IF APPROPRIATE) |    |  |
|                     |                 |      |                          |       |          |                                 |    |  |
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|                     | <br>            |      | FOREIGN PATENT DOCUMENTS |       |          |                                 |    |  |
| EXAMINER            | DOCUMENT NUMBER | DATE | COUNTRY                  | CLASS | SUBCLASS | SS TRANSLATION                  |    |  |
| INITIAL             |                 |      |                          |       |          | YES                             | NO |  |
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| EXAMINER |         | DOCUMENT NUMBER |  | DATE | COUNTRY | CLASS | SUBCLASS | TRANSLATION |   |
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| EXAMINER<br>INITIAL | OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.) |   |  |  |  |  |  |
|---------------------|--|---|--|--|--|--|--|
| m                   | A  | Dinesh Chopra and Ian Ivar Suni, "An Optical Method for Monitoring Metal Contamination during Aqueous Processing of Silicon Wafers", J. Electrochem. Soc., Vol. 145, No. 5, May 1998, pp. 1688-1692.  |  |  |  |  |  |
| Ju.                 | В  | Dinesh Chopra, Ian Ivar Suni and Ahmed A. Busnaina, "Cu Dissolution from Si(111) into an SC-1 Process Solution", J. Electrochem. Soc., Vol. 145, No. 4, April 1998, pp. L60-61.   |  |  |  |  |  |
| Á                   | С  | Peter Singer, Editor-in-Chief, "Copper CMP: A Question of Tradeoffs", Semiconductor International, http://www.semiconductor.net/semiconductor/issues/issues/2000/200005/six0005cmp.asp, May 2000, 11 pages.   |  |  |  |  |  |
| AN.                 | D  | "The CMP Business Unit", Rodel Products, http://www.rodel.com/Products/CMP.asp, 1998-2000, 13 pages.  |  |  |  |  |  |
| \$M                 | E  | Kurt Hery and Dr. David P. Norwood, "Study of the Refractive Index Increment of Polyelectrolytes and Neutral Polymers", Southeastern Louisiana University, http://www.selu.edu/Academics/ArtsC\Sciences/connections/journal1/k-hery/Hery.html, 7 pages. |  |  |  |  |  |
| M                   | F  | lqbal Ali and Sudipto R. Roy, "Pad conditioning in interlayer dielectric CMP", Texas Instruments, http://www.semipark.co/Pad%20conditioning%20in%20interlayer%20dielectric%20CMP.ht, June 1, 1997, 6 pages.   |  |  |  |  |  |
| 7//                 | G  | "Chemical Mechanical Planarization (CMP)", S.C. Solutions, http://www.scsolutions.com/smp.html, 4 pages.  |  |  |  |  |  |

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